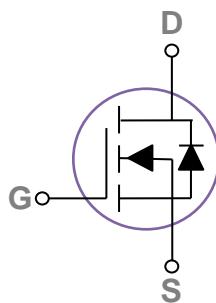
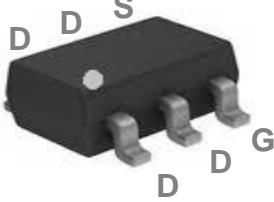


General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

SOT23-6 Pin Configuration



BVDSS	RDS(ON)	ID
20V	23mΩ	6A

Features

- 20V, 6A, $RDS(ON) = 23m\Omega$ @ $VGS = 4.5V$
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

Applications

- MB / VGA / Vcore
- Load Switch
- Hand-Held Instrument

Absolute Maximum Ratings $T_c=25^\circ C$ unless otherwise noted

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	20	V
V_{GS}	Gate-Source Voltage	± 10	V
I_D	Drain Current – Continuous ($T_A=25^\circ C$)	6	A
	Drain Current – Continuous ($T_A=70^\circ C$)	4.8	A
I_{DM}	Drain Current – Pulsed ¹	24	A
P_D	Power Dissipation ($T_A=25^\circ C$)	1.56	W
	Power Dissipation – Derate above $25^\circ C$	125	mW/ $^\circ C$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ C$

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	80	$^\circ C/W$

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)
Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_{\text{D}}=250\mu\text{A}$	20	---	---	V
I_{DSS}	Drain-Source Leakage Current	$V_{\text{DS}}=20\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	1	μA
		$V_{\text{DS}}=16\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=125^\circ\text{C}$	---	---	10	μA
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 10\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA

On Characteristics

$\text{R}_{\text{DS(ON)}}$	Static Drain-Source On-Resistance ³	$V_{\text{GS}}=4.5\text{V}$, $I_{\text{D}}=2.5\text{A}$	---	19	23	$\text{m}\Omega$
		$V_{\text{GS}}=2.5\text{V}$, $I_{\text{D}}=2\text{A}$	---	23	30	
		$V_{\text{GS}}=1.8\text{V}$, $I_{\text{D}}=1.5\text{A}$	---	32	45	
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$, $I_{\text{D}}=250\mu\text{A}$	0.4	0.6	0.8	V
g_{fs}	Forward Transconductance	$V_{\text{DS}}=10\text{V}$, $I_{\text{D}}=1\text{A}$	---	5	---	S

Dynamic and switching Characteristics

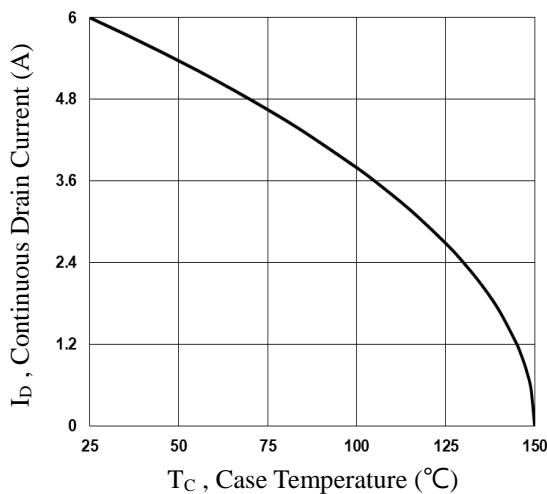
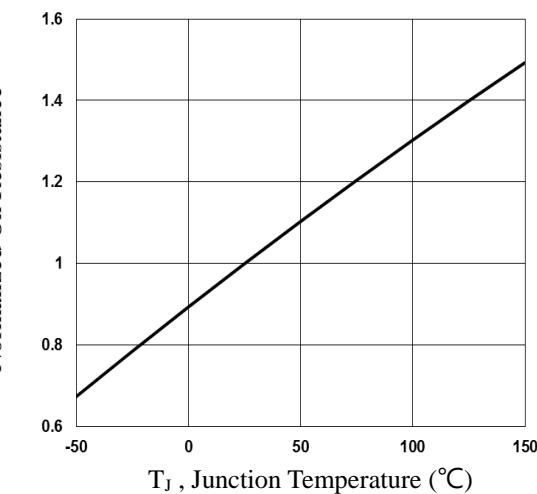
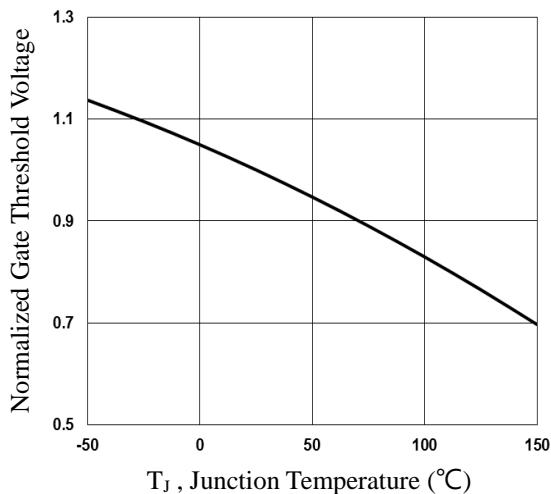
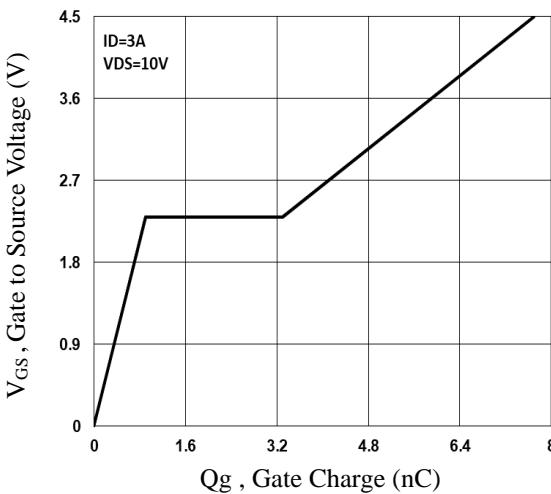
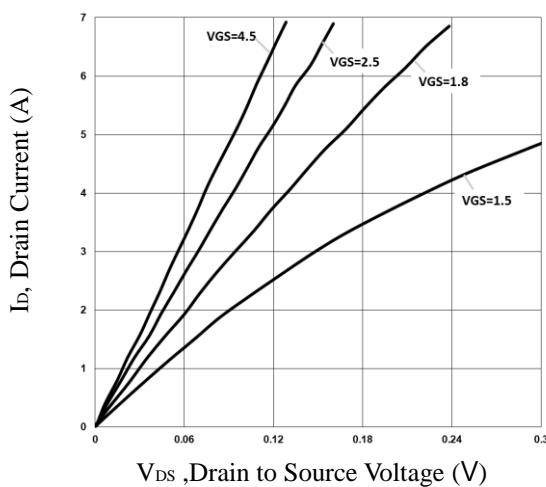
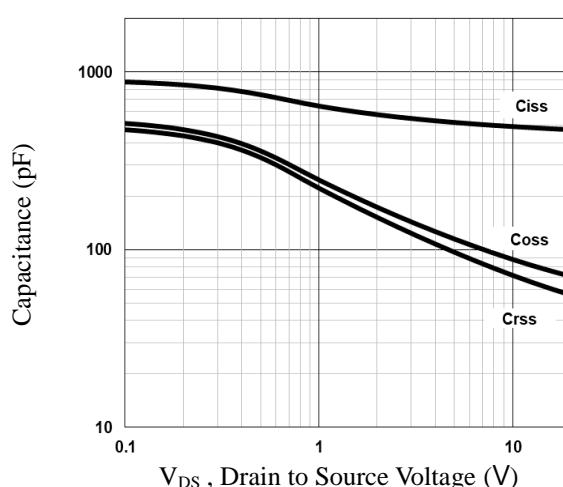
Q_g	Total Gate Charge ^{2,3}	$V_{\text{DS}}=10\text{V}$, $V_{\text{GS}}=4.5\text{V}$, $I_{\text{D}}=3\text{A}$	---	10.4	15	nC
Q_{gs}	Gate-Source Charge ^{2,3}		---	0.9	2	
Q_{gd}	Gate-Drain Charge ^{2,3}		---	2	3.5	
$T_{\text{d(on)}}$	Turn-On Delay Time ^{2,3}	$V_{\text{DD}}=10\text{V}$, $V_{\text{GS}}=4.5\text{V}$, $R_{\text{G}}=6\Omega$ $I_{\text{D}}=3\text{A}$	---	4.1	6.2	nS
T_r	Rise Time ^{2,3}		---	11.6	18	
$T_{\text{d(off)}}$	Turn-Off Delay Time ^{2,3}		---	23.9	36	
T_f	Fall Time ^{2,3}		---	7.6	12	
C_{iss}	Input Capacitance	$V_{\text{DS}}=10\text{V}$, $V_{\text{GS}}=0\text{V}$, $F=1\text{MHz}$	---	490	750	pF
C_{oss}	Output Capacitance		---	90	140	
C_{rss}	Reverse Transfer Capacitance		---	70	120	
R_g	Gate Resistance	$V_{\text{GS}}=0\text{V}$, $V_{\text{DS}}=0\text{V}$, $F=1\text{MHz}$	---	1.5	---	Ω

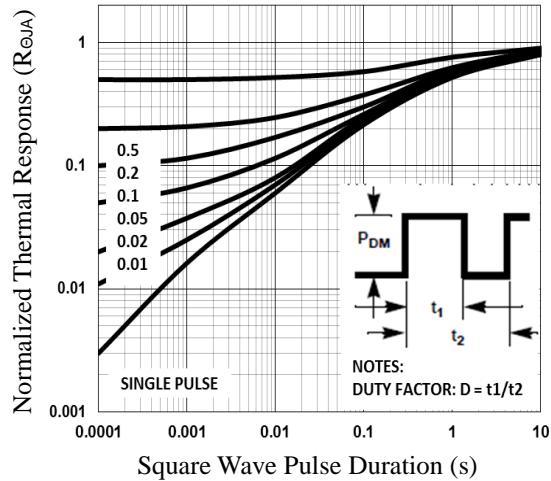
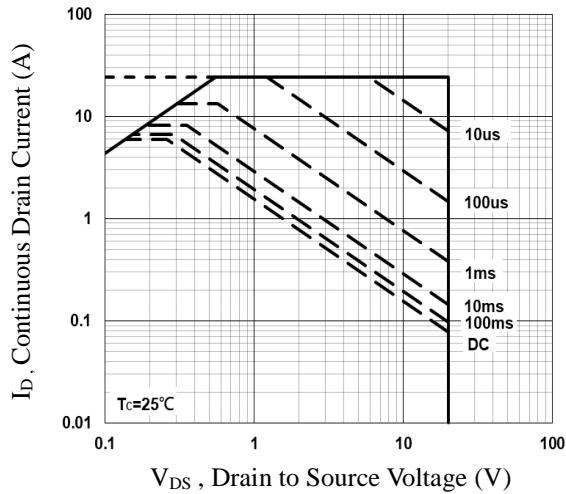
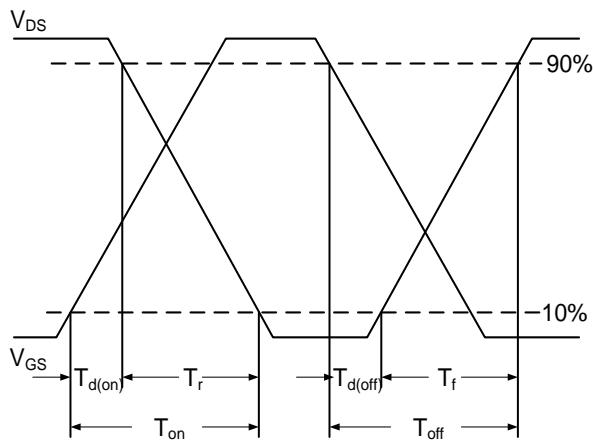
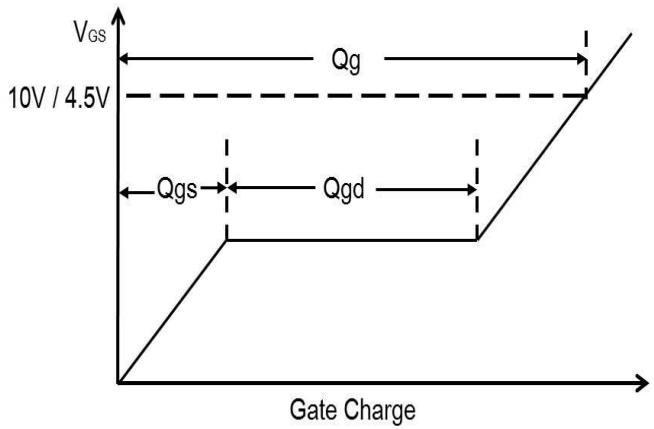
Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current	$V_G=V_D=0\text{V}$, Force Current	---	---	6	A
I_{SM}	Pulsed Source Current ³		---	---	12	A
V_{SD}	Diode Forward Voltage ³	$V_{\text{GS}}=0\text{V}$, $I_{\text{S}}=1\text{A}$, $T_J=25^\circ\text{C}$	---	---	1	V

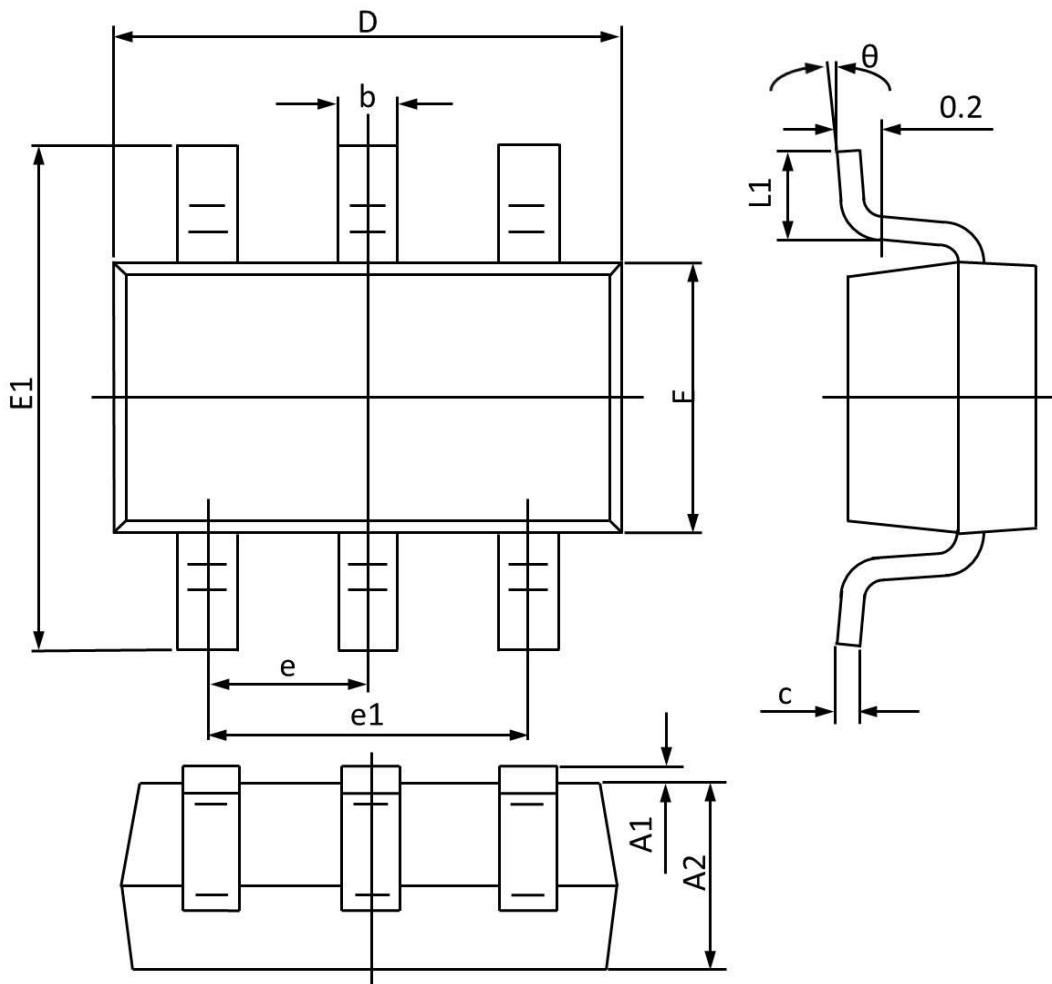
Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
3. Essentially independent of operating temperature.


Fig.1 Continuous Drain Current vs. T_c

Fig.2 Normalized RD_{SON} vs. T_j

Fig.3 Normalized V_{th} vs. T_j

Fig.4 Gate Charge Waveform

Fig.5 Typical Output Characteristics

Fig.6 Capacitance Characteristics


Fig.7 Normalized Transient Response

Fig.8 Maximum Safe Operation Area

Fig.9 Switching Time Waveform

Fig.10 Gate Charge Waveform

SOT23-6 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A1	---	0.150	---	0.006
A2	0.900	1.300	0.035	0.051
b	0.300	0.500	0.012	0.019
c	0.100	0.200	0.004	0.008
D	2.800	3.050	0.110	0.120
E1	2.600	3.000	0.103	0.118
F	1.500	1.800	0.059	0.071
e	0.950 TYP		0.037 TYP	
e1	1.900 TYP		0.075 TYP	
L1	0.250	0.600	0.010	0.024
θ	0°	8°	0°	8°